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(54) SEMICONDUCTOR DEVICE
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(**) Term: 15 Years

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
438/15, 25, 26, 51, 55, 63, 64, 106
CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
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224/08054; H01L 23/58; H05B 41/14;
G02B 6/4201; G02B 6/4256; G02B
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G02B 6/428; G02B 6/4281; H05K 1/14;
H05K 1/141;

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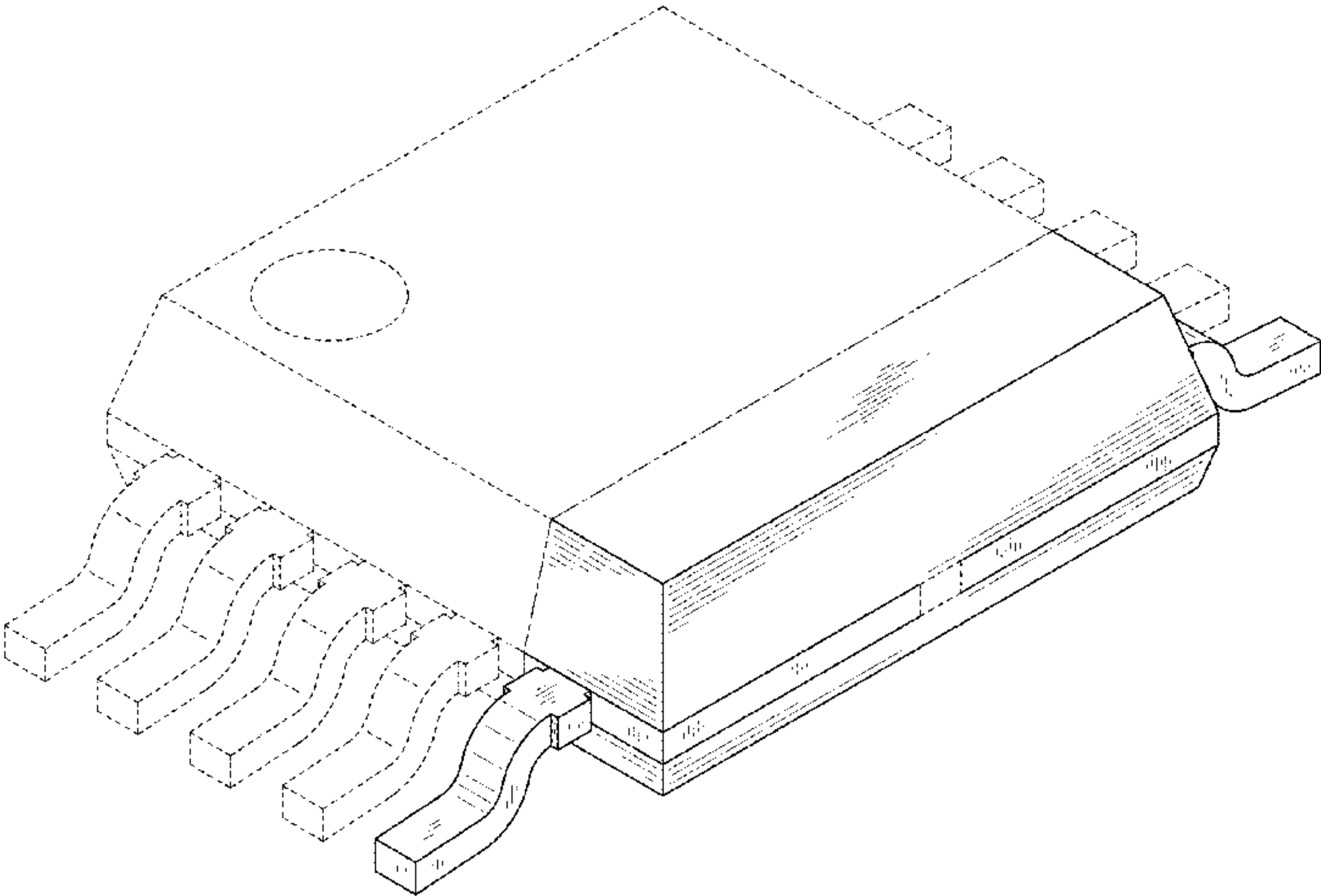
(57) CLAIM

The ornamental design for a semiconductor device, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and right side perspective view of a semiconductor device showing my new design;
FIG. 2 is a rear, bottom and left side perspective view thereof;
FIG. 3 is a front view thereof, the rear view being a mirror image of FIG. 3;
FIG. 4 is a top plan view thereof;
FIG. 5 is a bottom plan view thereof; and,
FIG. 6 is a right side view thereof.
The even broken lines illustrate portions of the semiconductor device that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



(58) **Field of Classification Search**
CPC H05K 1/142; H05K 1/144; H05K 1/18;
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See application file for complete search history.

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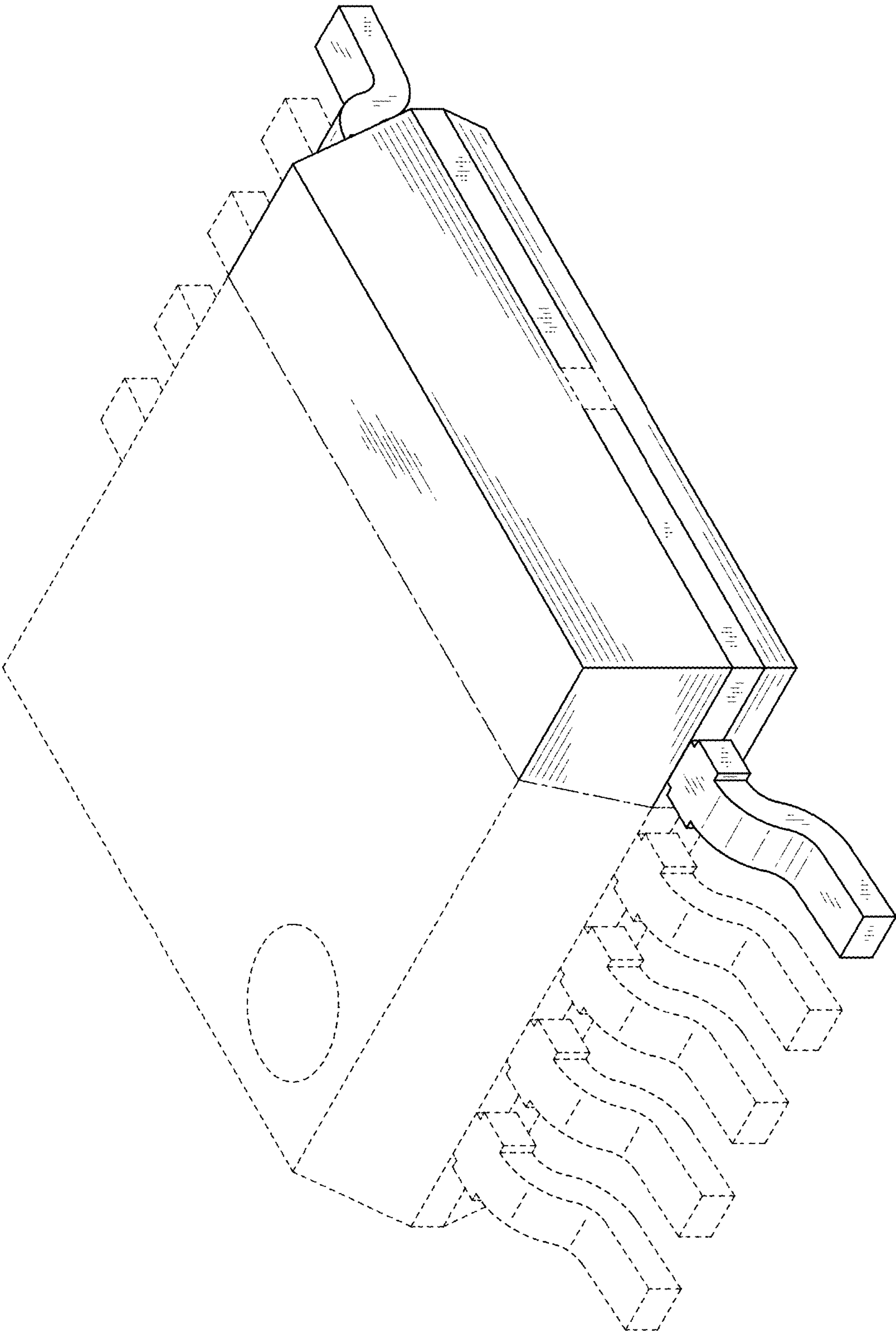
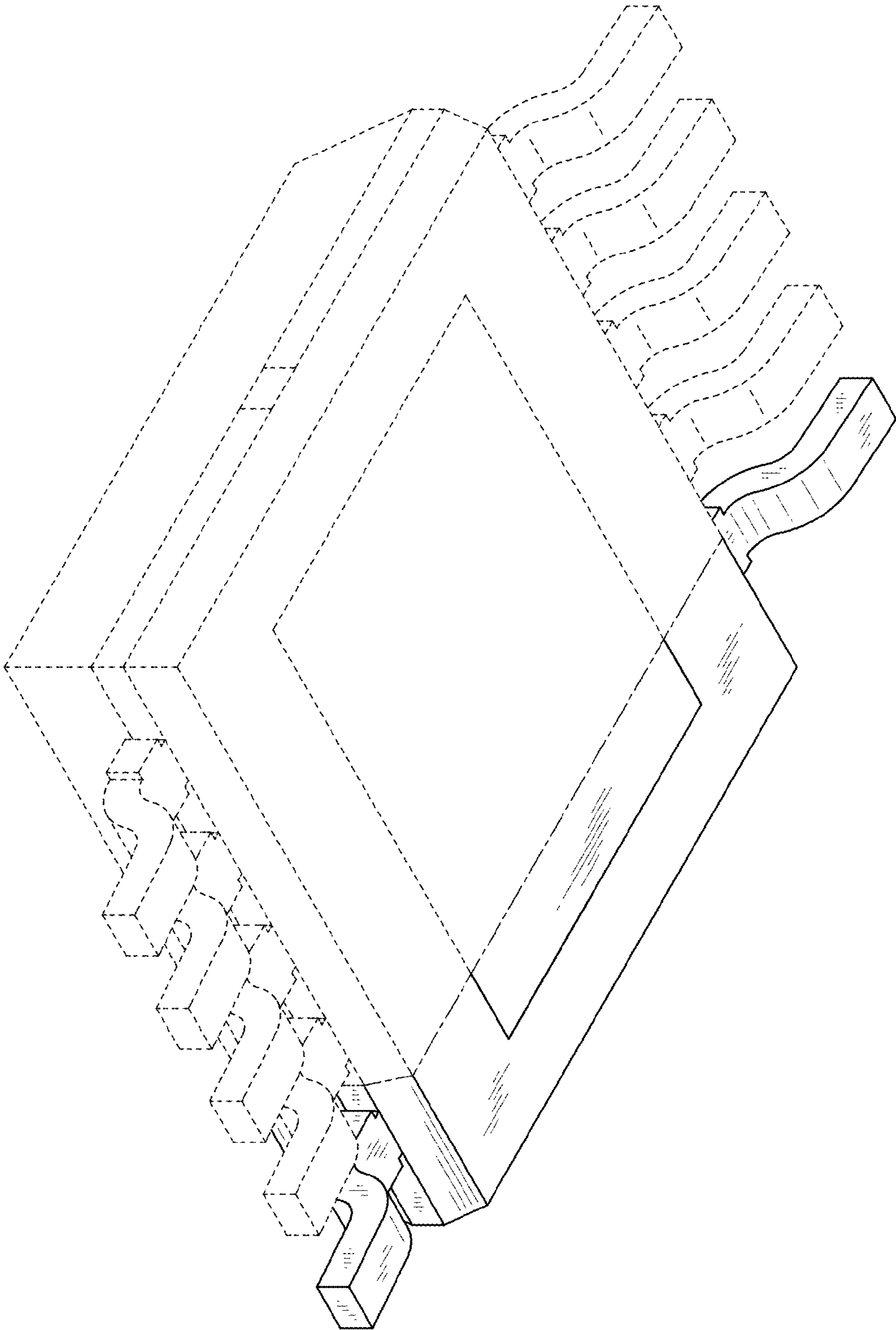


FIG.1

FIG.2



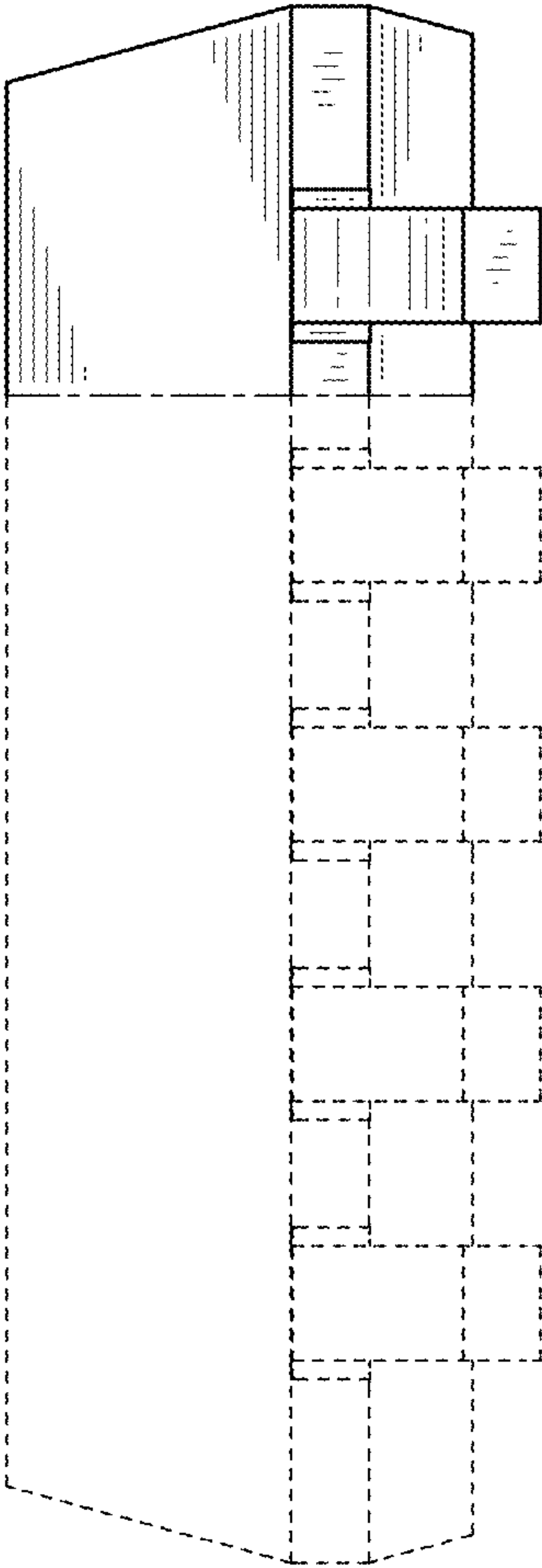


FIG.3

FIG.4

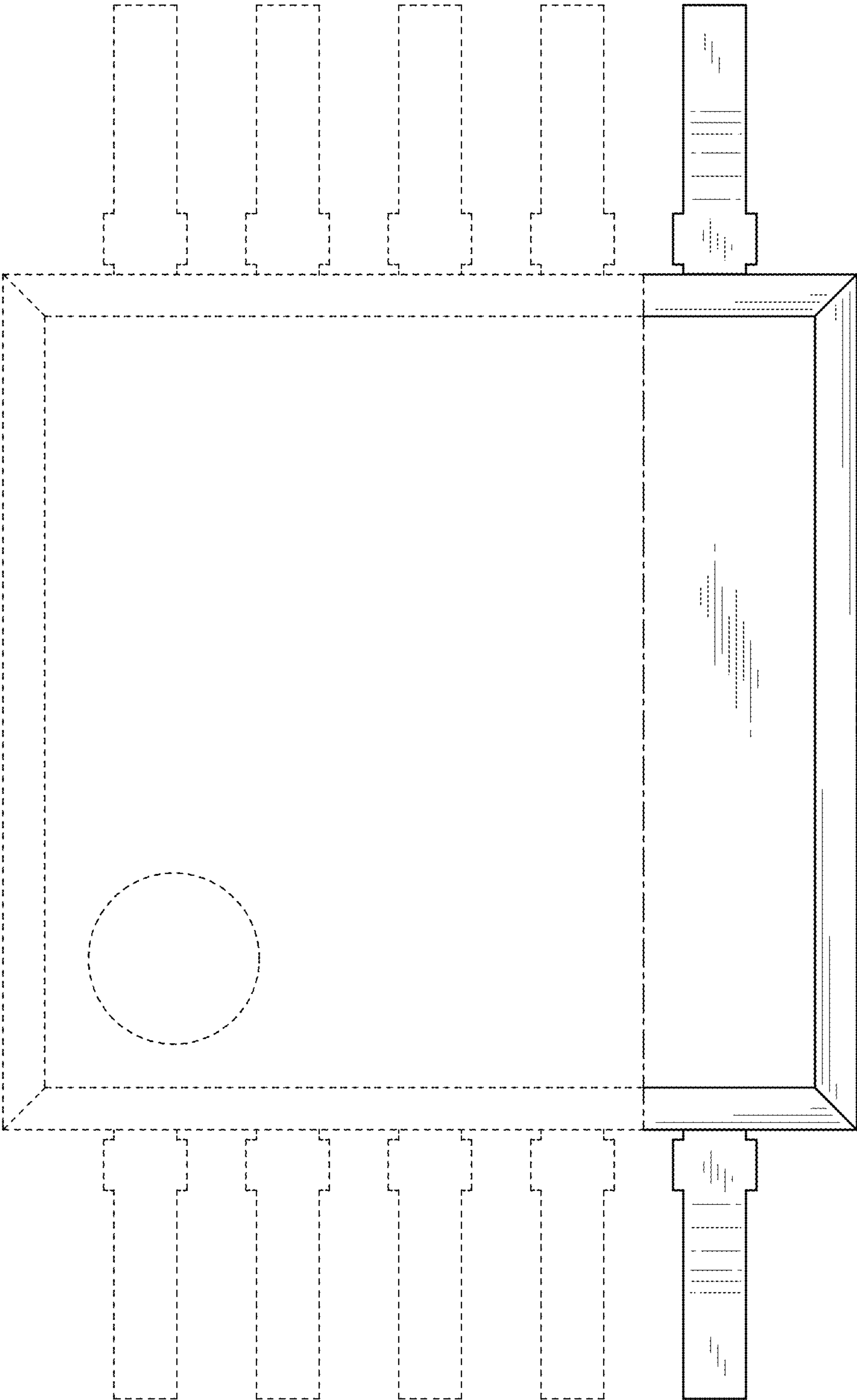


FIG.5

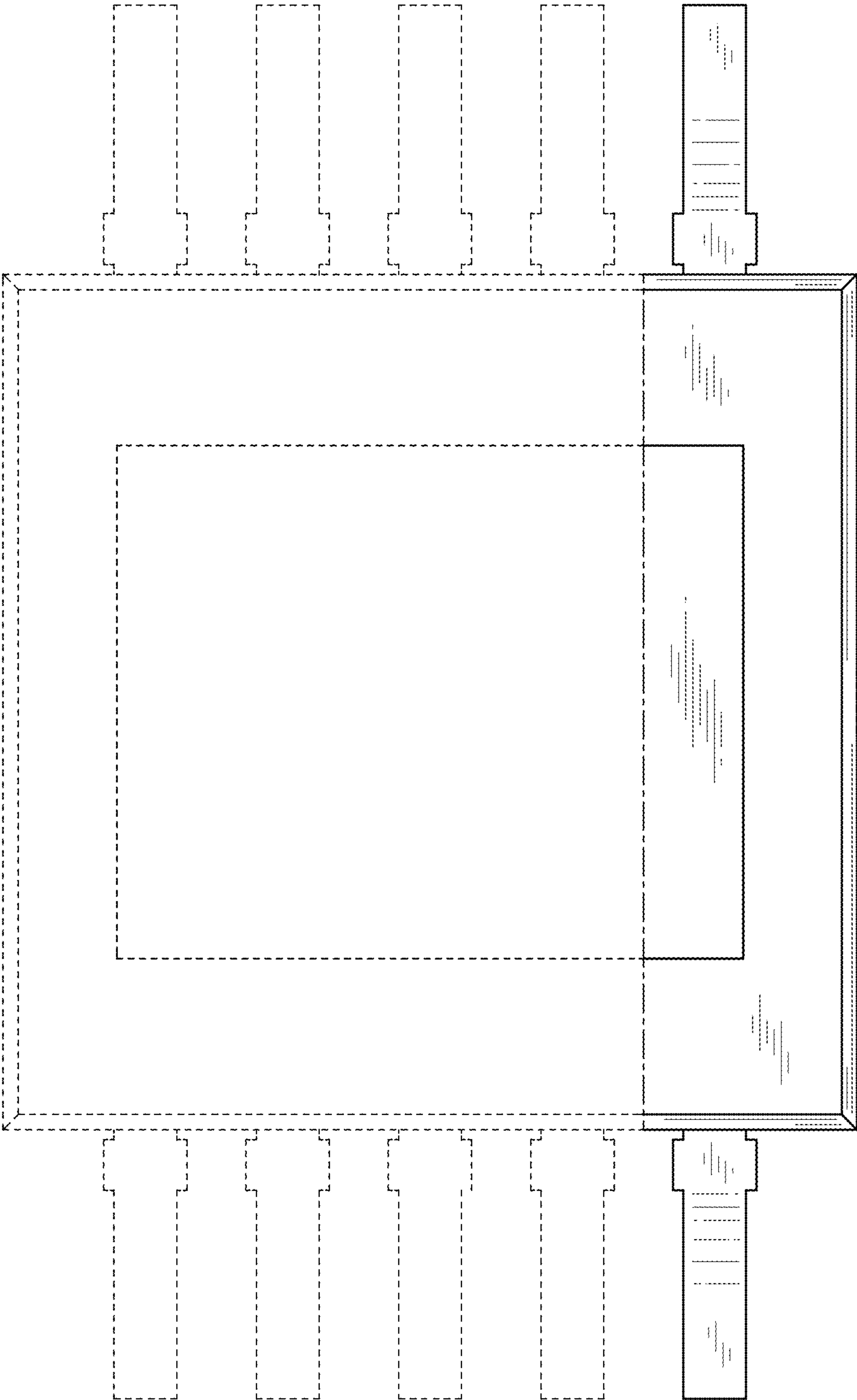


FIG.6

